

44 V Supply Maximum Ratings ±15 V Analog Signal Range

Ultralow Power Dissipation (3.9 μ W)

Break-Before-Make Switching Action

Plug-in Replacement for DG411/DG412/DG413

Low On Resistance (<24 Ω)

Low Leakage (<0.25 nA)

TTL/CMOS Compatible

Audio and Video Switching

Automatic Test Equipment

Precision Data Acquisition

Battery Powered Systems

Communication Systems

Fast Switching Times

t_{ON} <165 ns

t_{OFF} <130 ns

APPLICATIONS

FEATURES

LC²MOS Precision Quad SPST Switches

ADG431/ADG432/ADG433

FUNCTIONAL BLOCK DIAGRAMS



GENERAL DESCRIPTION

Sample Hold Systems

The ADG431, ADG432 and ADG433 are monolithic CMOS devices comprising four independently selectable switches. They are designed on an enhanced LC^2MOS process which provides low power dissipation yet gives high switching speed and low on resistance.

The on resistance profile is very flat over the full analog input range ensuring excellent linearity and low distortion when switching audio signals. Fast switching speed coupled with high signal bandwidth also make the parts suitable for video signal switching. CMOS construction ensures ultralow power dissipation making the parts ideally suited for portable and battery powered instruments.

The ADG431, ADG432 and ADG433 contain four independent SPST switches. The ADG431 and ADG432 differ only in that the digital control logic is inverted. The ADG431 switches are turned on with a logic low on the appropriate control input, while a logic high is required for the ADG432. The ADG433 has two switches with digital control logic similar to that of the ADG431 while the logic is inverted on the other two switches.

Each switch conducts equally well in both directions when ON and has an input signal range which extends to the supplies. In the OFF condition, signal levels up to the supplies are blocked. All switches exhibit break before make switching action for use in multiplexer applications. Inherent in the design is low charge injection for minimum transients when switching the digital inputs.

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PRODUCT HIGHLIGHTS

- Extended Signal Range The ADG431, ADG432 and ADG433 are fabricated on an enhanced LC²MOS process giving an increased signal range
- which extends fully to the supply rails.
- 2. Ultralow Power Dissipation
- 3. Low R_{ON}
- 4. Break-Before-Make Switching This prevents channel shorting when the switches are configured as a multiplexer.
- 5. Single Supply Operation

For applications where the analog signal is unipolar, the ADG431, ADG432 and ADG433 can be operated from a single rail power supply. The parts are fully specified with a single +12 V power supply and will remain functional with single supplies as low as +5 V.

ADG431/ADG432/ADG433-SPECIFICATIONS¹

Dual Supply ($V_{DD} = +15 V \pm 10\%$, $V_{SS} = -15 V \pm 10\%$, $V_L = +5 V \pm 10\%$, GND = 0 V, unless otherwise noted)

	В	Versions -40°C to	TV	/ersions -55°C to		
Parameter	+25°C	+85°C	+25°C	+125°C	Units	Test Conditions/Comments
ANALOG SWITCH						
Analog Signal Range		V_{DD} to V_{SS}		V_{DD} to V_{SS}	V	
R _{ON}	17	55 55	17	DD 55	Ω typ	$V_D = \pm 8.5 \text{ V}, I_S = -10 \text{ mA};$
0N	24	26	24	27	Ω max	$V_{DD} = +13.5 \text{ V}, V_{SS} = -13.5 \text{ V}$
R_{ON} vs. V_D (V_S)	15		15		% typ	
R_{ON} Drift	0.5		0.5		%/°C typ	
R _{ON} Match	5		5		% typ	$V_{\rm D} = 0 \text{ V}, \text{ I}_{\rm S} = -10 \text{ mA}$
LEAKAGE CURRENTS						$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$
Source OFF Leakage I_S (OFF)	±0.05		±0.05		nA typ	$V_D = \pm 15.5 \text{ V}, V_S = \pm 15.5 \text{ V};$
Source off Leakage is (011)	± 0.05 ± 0.25	± 2	± 0.05 ± 0.25	±15	nA max	Test Circuit 2
Drain OFF Leakage I _D (OFF)	± 0.25 ± 0.05	12	± 0.25 ± 0.05	±1)	nA typ	$V_D = \pm 15.5 \text{ V}, V_S = \mp 15.5 \text{ V};$
Dialit OFT Leakage ID (OFT)	± 0.05 ± 0.25	± 2	± 0.05 ± 0.25	±15	nA max	Test Circuit 2
Channel ON Leakage I. J. (ON)	± 0.25 ± 0.1	12	± 0.25 ± 0.1	±1)		
Channel ON Leakage I _D , I _S (ON)		+2	± 0.1 ± 0.35	± 17	nA typ	$V_D = V_S = \pm 15.5 V;$ Test Circuit 3
	±0.35	±3	±0.35	±17	nA max	Test Circuit 3
DIGITAL INPUTS						
Input High Voltage, V _{INH}		2.4		2.4	V min	
Input Low Voltage, V _{INL}		0.8		0.8	V max	
Input Current						
I _{INL} or I _{INH}	0.005		0.005		μA typ	$V_{IN} = V_{INL}$ or V_{INH}
		± 0.02		± 0.02	μA max	
C _{IN} Digital Input Capacitance	9		9		pF typ	
DYNAMIC CHARACTERISTICS ²						$V_{DD} = +15 \text{ V}, V_{SS} = -15 \text{ V}$
t _{ON}	90		90		ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
		165		175	ns max	$V_s = \pm 10 V$; Test Circuit 4
t _{OFF}	60		60		ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
		130		145	ns max	$V_s = \pm 10 V$; Test Circuit 4
Break-Before-Make Time Delay, t _D	25		25		ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
(ADG433 Only)						$V_{S1} = V_{S2} = +10 V;$
						Test Circuit 5
Charge Injection	5		5		pC typ	$V_{S} = 0 V, R_{S} = 0 \Omega, C_{L} = 10 nF;$
						Test Circuit 6
OFF Isolation	68		68		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$
						Test Circuit 7
Channel-to-Channel Crosstalk	85		85		dB typ	$R_L = 50 \Omega, C_L = 5 pF, f = 1 MHz$
C _s (OFF)	0		0		nE tren	Test Circuit 8
	9 9		9 9		pF typ pF typ	f = 1 MHz
$C_{\rm D}$ (OFF)	35		35			f = 1 MHz f = 1 MHz
$C_{\rm D}, C_{\rm S}$ (ON)	33		33		pF typ	
POWER REQUIREMENTS						$V_{DD} = +16.5 V, V_{SS} = -16.5 V$ Digital Inputs = 0 V or 5 V
I _{DD}	0.0001		0.0001		μA typ	
	0.1	0.2	0.1	0.2	μA max	
I _{SS}	0.0001		0.0001		μA typ	
	0.1	0.2	0.1	0.2	μA max	
IL	0.0001		0.0001		μA typ	
	0.1	0.2	0.1	0.2	μA max	
Power Dissipation		7.7		7.7	µW max	

NOTES ¹Temperature ranges are as follows: B Versions: -40 °C to +85°C; T Versions: -55°C to +125°C.

²Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

Single Supply (V_{DD} = +12 V ± 10%, V_{SS} = 0 V, V_L = +5 V ± 10%, GND = 0 V, unless otherwise noted)

	B	Versions –40°C to	TV	′ersions –55°C to		
Parameter	+25°C	+85°C	+25°C	+125°C	Units	Test Conditions/Comments
ANALOG SWITCH						
Analog Signal Range		$0 \mathrm{~V}$ to V_{DD}		0 V to V_{DD}	v	
R _{ON}	28	22	28	22	Ω typ	$0 < V_D < 8.5 V$, $I_S = -10 mA$;
	42	45	42	45	Ω max	$V_{DD} = +10.8 V$
R_{ON} vs. V_D (V _S)	20		20		% typ	
R _{ON} Drift	0.5		0.5		%/°C typ	
R _{ON} Match	5		5		% typ	$V_{\rm D} = 0 \text{ V}, \text{ I}_{\rm S} = -10 \text{ mA}$
LEAKAGE CURRENTS						$V_{DD} = +13.2 \text{ V}$
Source OFF Leakage I _S (OFF)	± 0.04		± 0.04		nA typ	$V_{\rm DD} = 12.2/1$ V, V _S = 1/12.2 V;
Source OFT Leakage IS (OFT)	± 0.04 ± 0.25	± 2	± 0.04 ± 0.25	±15	nA typ	$v_D = 12.2/1 v_1 v_2 = 1/12.2 v_1$ Test Circuit 2
Drain OFF Lashaga L (OFF)		± 2		±15		
Drain OFF Leakage I_D (OFF)	± 0.04		± 0.04	115	nA typ	$V_D = 12.2/1 \text{ V}, V_S = 1/12.2 \text{ V};$
	± 0.25	± 2	±0.25	±15	nA max	Test Circuit 2
Channel ON Leakage I _D , Is (ON)	± 0.01		± 0.01		nA typ	$V_D = V_S = +12.2 \text{ V/+1 V};$
	±0.3	±3	±0.3	±17	nA max	Test Circuit 3
DIGITAL INPUTS						
Input High Voltage, V _{INH}		2.4		2.4	V min	
Input Low Voltage, V _{INL}		0.8		0.8	V max	
Input Current						
I _{INL} or I _{INH}	0.005		0.005		μA typ	$V_{IN} = V_{INI}$ or V_{INH}
		± 0.01		± 0.01	µA max	
C _{IN} Digital Input Capacitance	9		9		pF typ	
DYNAMIC CHARACTERISTICS ²			-		I -51	$\mathbf{X} = 112 \mathbf{X} \mathbf{X} = 0 \mathbf{X}$
	165		165			$V_{DD} = +12 V, V_{SS} = 0 V$
t _{ON}	105	240	105	240	ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
	(0)	240	(0)	240	ns max	$V_s = +8 V$; Test Circuit 4
t _{OFF}	60	115	60	115	ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
		115		115	ns max	$V_s = +8 V$; Test Circuit 4
Break-Before-Make Time Delay, t _D	25		25		ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
(ADG433 Only)						$V_{S1} = V_{S2} = +10 V;$
					_	Test Circuit 5
Charge Injection	25		25		pC typ	$V_{\rm S} = 0 \text{ V}, \text{R}_{\rm S} = 0 \Omega, \text{C}_{\rm L} = 10 \text{nF};$
						Test Circuit 6
OFF Isolation	68		68		dB typ	$R_L = 50 \Omega, C_L = 5 pF, f = 1 MHz$
						Test Circuit 7
Channel-to-Channel Crosstalk	85		85		dB typ	$R_L = 50 \Omega, C_L = 5 pF, f = 1 MHz$
						Test Circuit 8
C _S (OFF)	9		9		pF typ	f = 1 MHz
C _D (OFF)	9		9		pF typ	f = 1 MHz
C_D, C_S (ON)	35		35		pF typ	f = 1 MHz
POWER REQUIREMENTS						$V_{DD} = +13.2 V$
						Digital Inputs = $0 \text{ V or } 5 \text{ V}$
I _{DD}	0.0001		0.0001		μA typ	
-עע	0.0001	0.1	0.03	0.1	μA max	
IL	0.0001	~**	0.0001		μA typ	
▲L	0.0001	0.1	0.0001	0.1	μA typ μA max	$V_{L} = +5.25 V$
Power Dissipation	0.05	1.9	0.05	0.1 1.9	μW max	
Power Dissipation		1.9		1.9	µw max	

NOTES

 $^lTemperature ranges are as follows: B Versions: –40 <math display="inline">^oC$ to +85 $^oC;$ T Versions: –55 oC to +125 $^oC.$

²Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

Truth Table (ADG431/ADG432)

ADG431 In	ADG432 In	Switch Condition
0	1	ON
1	0	OFF

Truth Table (ADG433)

Logic	Switch 1, 4	Switch 2, 3	
0	OFF	ON	
1	ON	OFF	

ABSOLUTE MAXIMUM RATINGS
$(T_A = +25^{\circ}C \text{ unless otherwise noted})$
V_{DD} to V_{SS} +44 V
V _{DD} to GND0.3 V to +25 V
V _{SS} to GND
V_L to GND
Analog, Digital Inputs ² $V_{SS} - 2 V$ to $V_{DD} + 2 V$ or
30 mA, Whichever Occurs First
Continuous Current, S or D 30 mA
Peak Current, S or D 100 mA
(Pulsed at 1 ms, 10% Duty Cycle max)
Operating Temperature Range
Industrial (B Version)40°C to +85°C
Extended (T Version)55°C to +125°C
Storage Temperature Range65°C to +150°C
Junction Temperature
Cerdip Package, Power Dissipation
CAUTION

θ_{JA} , Thermal Impedance
Lead Temperature, Soldering (10 sec) +300°C
Plastic Package, Power Dissipation
θ_{JA} , Thermal Impedance
Lead Temperature, Soldering (10 sec) +260°C
SOIC Package, Power Dissipation
θ_{JA} , Thermal Impedance
Lead Temperature, Soldering
Vapor Phase (60 sec) +215°C
Infrared (15 sec) +220°C

NOTES

¹Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

²Overvoltages at IN, S or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG431/ADG432/ADG433 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PIN CONFIGURATION (DIP/SOIC)					
		L	IN2		
IN1 1	•	16	INZ		
D1 2		15	D2		
S1 3	ADG431 ADG432	14	S2		
V _{SS} 4	ADG433	13	V _{DD}		
GND 5	TOP VIEW (Not to Scale)	12	VL		
S4 6		11	S3		
D4 7		10	D3		
IN4 8		9	IN3		

ORDERING GUIDE

T	
Temperature Range	Package Options ²
-40°C to +85°C	N-16
-40°C to +85°C	R-16A
–55°C to +125°C	Q-16
-40°C to +85°C	R-16A ³
-40°C to +85°C	N-16
-40°C to +85°C	R-16A
–55°C to +125°C	Q-16
-40°C to +85°C	R-16A ³
-40°C to +85°C	N-16
-40°C to +85°C	R-16A
-40°C to +85°C	R-16A ³
	$\begin{array}{c} -40^{\circ}\text{C to } +85^{\circ}\text{C} \\ -40^{\circ}\text{C to } +85^{\circ}\text{C} \\ -55^{\circ}\text{C to } +125^{\circ}\text{C} \\ -40^{\circ}\text{C to } +85^{\circ}\text{C} \\ -40^{\circ}\text{C to } +85^{\circ}\text{C} \\ -40^{\circ}\text{C to } +85^{\circ}\text{C} \\ -55^{\circ}\text{C to } +125^{\circ}\text{C} \\ -40^{\circ}\text{C to } +85^{\circ}\text{C} \\ \end{array}$

NOTES

¹To order MIL-STD-883, Class B processed parts, add /883B to T grade part numbers. ²N = Plastic DIP; R = 0.15" Small Outline IC (SOIC); Q = Cerdip. ³Trench isolated, latch-up proof parts. See Trench Isolation section.

TERMINOLOGY

V _{DD}	Most positive power supply potential.	C _s (OFF)	"OFF" switch source capacitance.
V _{SS}	Most negative power supply potential in dual	C _D (OFF)	"OFF" switch drain capacitance.
	supplies. In single supply applications, it may be	$C_D, C_S (ON)$	"ON" switch capacitance.
	connected to GND.	C _{IN}	Input Capacitance to ground of a digital input.
V_L	Logic power supply (+5 V).	t _{ON}	Delay between applying the digital control input
GND	Ground (0 V) reference.		and the output switching on.
S	Source terminal. May be an input or output.	t _{OFF}	Delay between applying the digital control input
D	Drain terminal. May be an input or output.		and the output switching off.
IN	Logic control input.	t _D	"OFF" time or "ON" time measured between the
R _{ON}	Ohmic resistance between D and S.		90% points of both switches, when switching
R_{ON} vs. V_D (V_S)	The variation in R _{ON} due to a change in the ana-		from one address state to another.
	log input voltage with a constant load current.	Crosstalk	A measure of unwanted signal which is coupled
R _{ON} Drift	Change in R _{ON} vs. temperature.		through from one channel to another as a result
R _{ON} Match	Difference between the R _{ON} of any two switches.		of parasitic capacitance.
I _S (OFF)	Source leakage current with the switch "OFF."	Off Isolation	A measure of unwanted signal coupling through an
I _D (OFF)	Drain leakage current with the switch "OFF."		"OFF" switch.
$I_D, I_S (ON)$	Channel leakage current with the switch "ON."	Charge	A measure of the glitch impulse transferred from the
$V_D(V_S)$	Analog voltage on terminals D, S.	Injection	digital input to the analog output during switching.

Typical Performance Graphs



Figure 1. On Resistance as a Function of $V_{\text{D}}\left(V_{\text{S}}\right)$ Dual Supplies



Figure 2. On Resistance as a Function of V_D (V_S) for Different Temperatures



Figure 3. Leakage Currents as a Function of Temperature



Figure 4. On Resistance as a Function of $V_{\text{D}}\left(V_{\text{S}}\right)$ Single Supply



Figure 5. Supply Current vs. Input Switching Frequency



Figure 6. Leakage Currents as a Function of $V_D(V_S)$



Figure 7. Off Isolation vs. Frequency



Figure 8. Crosstalk vs. Frequency

TRENCH ISOLATION

In the ADG431A, ADG432A and ADG433A, an insulating oxide layer (trench) is placed between the NMOS and PMOS transistors of each CMOS switch. Parasitic junctions, which occur between the transistors in junction isolated switches, are eliminated, the result being a completely latch-up proof switch.

In junction isolation, the N and P wells of the PMOS and NMOS transistors from a diode that is reverse-biased under normal operation. However, during overvoltage conditions, this diode becomes forward biased. A silicon-controlled rectifier (SCR) type circuit is formed by the two transistors causing a significant amplification of the current which, in turn, leads to latch up. With trench isolation, this diode is removed, the result being a latch-up proof switch.



Figure 9. Trench Isolation

APPLICATION

Figure 10 illustrates a precise, fast sample-and-hold circuit. An AD845 is used as the input buffer while the output operational amplifier is an AD711. During the track mode, SW1 is closed and the output V_{OUT} follows the input signal V_{IN} . In the hold mode, SW1 is opened and the signal is held by the hold capacitor C_{H} .

Due to switch and capacitor leakage, the voltage on the hold capacitor will decrease with time. The ADG431/ADG432/ ADG433 minimizes this droop due to its low leakage specifications. The droop rate is further minimized by the use of a polystyrene hold capacitor. The droop rate for the circuit shown is typically 30 μ V/ μ s.

A second switch SW2, which operates in parallel with SW1, is included in this circuit to reduce pedestal error. Since both switches will be at the same potential, they will have a differential effect on the op amp AD711 which will minimize charge injection effects. Pedestal error is also reduced by the compensation network R_C and C_C . This compensation network also reduces the hold time glitch while optimizing the acquisition time. Using the illustrated op amps and component values, the pedestal error has a maximum value of 5 mV over the ±10 V input range. Both the acquisition and settling times are 850 ns.



Figure 10. Fast, Accurate Sample-and-Hold

Test Circuits





Test Circuit 1. On Resistance

Test Circuit 2. Off Leakage

Test Circuit 3. On Leakage



Test Circuit 4. Switching Times



Test Circuit 5. Break-Before-Make Time Delay



Test Circuit 6. Charge Injection



Test Circuit 7. Off Isolation



Test Circuit 8. Channel-to-Channel Crosstalk

OUTLINE DIMENSIONS Dimensions shown in inches and (mm).







16-Lead SOIC (R-16A)



